

9. (Amended) A COG assembly comprising a semiconductor chip having electrodes provided thereon and a substrate glass board having electrodes provided thereon corresponding to the electrodes provided on the semiconductor chip, the electrodes provided on the semiconductor chip being held in direct connection with the corresponding electrodes provided on the substrate glass board by a connecting material, the connecting material having a tensile elongation percentage of at least 5% at 25°C, after being cured, and comprising an adhesive component comprising a thermosetting resin and 6-90 wt.% of a microparticulate elastomer product of natural or synthetic rubber having an average particle size of 30-300 nm and electroconductive particles.

REMARKS

In order to expedite the prosecution of the present application, Claims 8 and 9 have been amended to state that the adhesive component comprises a thermosetting resin and 60-90 wt.% of a microparticulate elastomer product of natural or synthetic rubber having an average particle size of 30-300 nm. Support for this amendment can be found on original specification page 8, lines 15-23. No new matter has been added. Since currently presented Claims 16 and 17 also provide support for the amendments to Claims 8 and 9, entry thereof is deemed proper under 37 CFR 1.116(b). Favorable consideration is respectfully solicited.

Claims 3 and 6-19 have been rejected under 35 USC 102(b) as being anticipated by Tomita. Claim 7 also has been rejected under 35 USC 103(a) as being unpatentable over Tomita in combination with Yamada. Applicants respectfully traverse these grounds of rejection and urge reconsideration in light of the following comments.